

JOM Call for papers

An official publication of The Minerals, Metals & Materials Society

Publication Date: *December 2018*

Manuscript Deadline: *July 1, 2018*

The Electronic Packaging and Interconnection Materials Committee is seeking papers on the topic of
Advances in Electronic Interconnection Materials

This topic will include papers on Pb-free solder development, advances in the understanding of joint reliability and emerging interconnection materials for harsh environments.

Typical paper length is 5,000 to 6,500 words for review papers, and 2,400 to 4,000 words for original papers.

Detailed author instructions are available at:

<http://www.tms.org/AuthorTools/>

Keywords for this topic:

Electronic materials; intermetallics; lead, zinc, and tin

Guest Editor for this *JOM* topic is Chris Gourlay:

c.gourlay@imperial.ac.uk

If you are interested in submitting a paper, upload your manuscript at

<https://www.editorialmanager.com/jomj/>

Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

For more information on *JOM*, please visit jom.tms.org